74HC244-Q100; 74HCT244-Q100

Octal buffer/line driver; 3-state

Rev. 1 — 7 August 2012

Product data sheet

General description

The 74HC244-Q100; 74HCT244-Q100 is an 8-bit buffer/line driver with 3-state outputs. The device can be used as two 4-bit buffers or one 8-bit buffer. The device features two output enables ($1\overline{OE}$ and $2\overline{OE}$), each controlling four of the 3-state outputs. A HIGH on $n\overline{OE}$ causes the outputs to assume a high-impedance OFF-state. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of V_{CC} .

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
 - ◆ Specified from -40 °C to +85 °C and from -40 °C to +125 °C
- Input levels:
 - ◆ For 74HC244-Q100: CMOS level
 - ◆ For 74HCT244-Q100: TTL level
- Octal bus interface
- Non-inverting 3-state outputs
- Multiple package options
- Complies with JEDEC standard no. 7 A
- ESD protection:
 - ◆ MIL-STD-883, method 3015 exceeds 2000 V
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - lacktriangle MM JESD22-A115-A exceeds 200 V (C = 200 pF, R = 0 Ω)

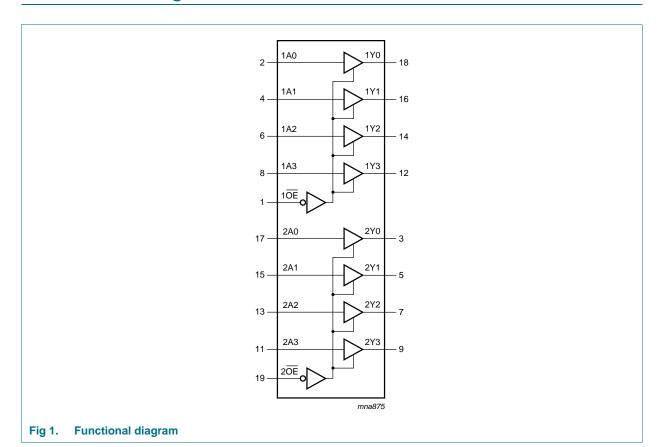


3. Ordering information

Table 1. Ordering information

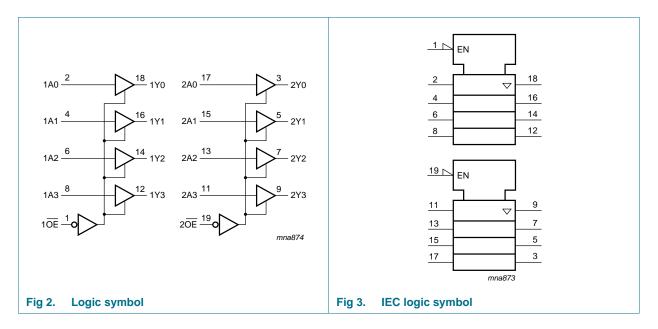
Type number	Package			
	Temperature range	Name	Description	Version
74HC244D-Q100	–40 °C to +125 °C	SO20	plastic small outline package; 20 leads;	SOT163-1
74HCT244D-Q100			body width 7.5 mm	
74HC244PW-Q100	–40 °C to +125 °C	TSSOP20	plastic thin shrink small outline package; 20 leads;	SOT360-1
74HCT244PW-Q100			body width 4.4 mm	
74HC244BQ-Q100	–40 °C to +125 °C	DHVQFN20	• · · · · · · · · · · · · · · · · · · ·	SOT764-1
74HCT244BQ-Q100			very thin quad flat package; no leads; 20 terminals; body 2.5 \times 4.5 \times 0.85 mm	

4. Functional diagram



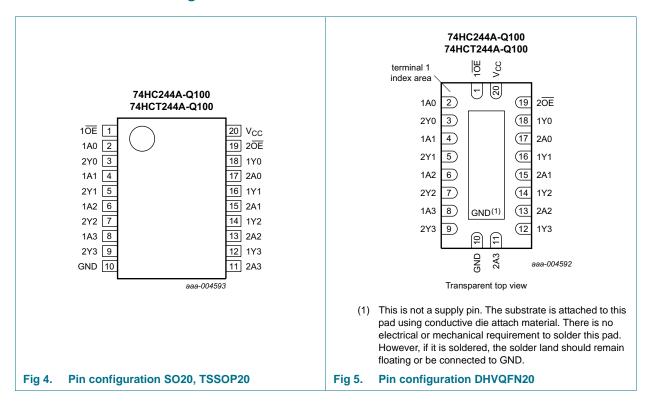
74HC_HCT244_Q100

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5. Pinning information

5.1 Pinning



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5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
10E, 20E	1, 19	output enable input (active LOW)
1A0, 1A1, 1A2, 1A3	2, 4, 6, 8	data input
2Y0, 2Y1, 2Y2, 2Y3	3, 5, 7, 9	bus output
GND	10	ground (0 V)
2A0, 2A1, 2A2, 2A3	17, 15, 13, 11	data input
1Y0, 1Y1, 1Y2, 1Y3	18, 16, 14, 12	bus output
V _{CC}	20	supply voltage

6. Functional description

Table 3. Function table[1]

Input nOE	Output	
nOE	nAn	nYn
L	L	L
L	Н	Н
Н	X	Z

^[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+7	V
I _{IK}	input clamping current	$V_I < -0.5 \text{ V or } V_I > V_{CC} + 0.5 \text{ V}$	-	±20	mA
I _{OK}	output clamping current	$V_O < -0.5 \text{ V or } V_O > V_{CC} + 0.5 \text{ V}$	-	±20	mA
I _O	output current	$-0.5 \text{ V} < \text{V}_{\text{O}} < \text{V}_{\text{CC}} + 0.5 \text{ V}$	-	±35	mA
I _{CC}	supply current		-	70	mA
I_{GND}	ground current		-70	-	mA
T _{stg}	storage temperature		-65	+150	°C
P _{tot}	total power dissipation		<u>[1]</u> _	500	mW

^[1] For SO20 packages: above 70 °C, P_{tot} derates linearly with 8 mW/K.
For TSSOP20 package: above 60 °C, P_{tot} derates linearly with 5.5 mW/K.
For DHVQFN20 packages: above 60 °C, P_{tot} derates linearly with 4.5 mW/K.

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8. Recommended operating conditions

Table 5. Recommended operating conditions

14010 01	recommended operating condition					
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
74HC244-C	2100					
V _{CC}	supply voltage		2.0	5.0	6.0	V
V_{I}	input voltage		0	-	V_{CC}	V
Vo	output voltage		0	-	V_{CC}	V
Δt/ΔV	·	$V_{CC} = 2.0 \text{ V}$	-	-	625	ns/V
		V _{CC} = 4.5 V	-	1.67	139	ns/V
		$V_{CC} = 6.0 \text{ V}$	-	-	83	ns/V
T _{amb}	ambient temperature		-40	-	+125	°C
74HCT244-	·Q100					
V _{CC}	supply voltage		4.5	5.0	5.5	V
VI	input voltage		0	-	V_{CC}	V
Vo	output voltage		0	-	V_{CC}	V
Δt/ΔV	input transition rise and fall rate	$V_{CC} = 4.5 \text{ V}$	-	1.67	139	ns/V
T _{amb}	ambient temperature		-40	-	+125	°C

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		25 °C		-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Тур	Max	Min	Max	Min	Max	
74HC244	1-Q100		-					1		
V _{IH}	HIGH-level	V _{CC} = 2.0 V	1.5	1.2	-	1.5	-	1.5	-	V
	input voltage	V _{CC} = 4.5 V	3.15	2.4	-	3.15	-	3.15	-	V
		V _{CC} = 6.0 V	4.2	3.2	-	4.2	-	4.2	-	V
IL -	LOW-level	V _{CC} = 2.0 V	-	8.0	0.5	-	0.5	-	0.5	V
	input voltage	V _{CC} = 4.5 V	-	2.1	1.35	-	1.35	-	1.35	V
		V _{CC} = 6.0 V	-	2.8	1.8	-	1.8	-	1.8	V
V _{OH}	HIGH-level	$V_I = V_{IH}$ or V_{IL}								
	output voltage	$I_{O} = -20 \mu A; V_{CC} = 2.0 V$	1.9	2.0	-	1.9	-	1.9	-	V
		$I_O = -20 \mu A$; $V_{CC} = 4.5 V$	4.4	4.5	-	4.4	-	4.4	-	V
		$I_O = -20 \mu A$; $V_{CC} = 6.0 \text{ V}$	5.9	6.0	-	5.9	-	5.9	-	V
		$I_{O} = -6.0 \text{ mA}; V_{CC} = 4.5 \text{ V}$	3.98	4.32	-	3.84	-	3.7	-	V
		$I_{O} = -7.8 \text{ mA}; V_{CC} = 6.0 \text{ V}$	5.48	5.81	-	5.34	-	5.2	-	V

Table 6. Static characteristics ...continued
At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		25 °C		-40 °C t	o +85 °C	-40 °C to +125 °C		Unit
			Min	Тур	Max	Min	Max	Min	Max	1
V _{OL}	LOW-level	$V_I = V_{IH}$ or V_{IL}			1	ı	ı	ı		
	output voltage	$I_O = 20 \mu A; V_{CC} = 2.0 V$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 20 \mu A; V_{CC} = 4.5 V$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 20 \mu A; V_{CC} = 6.0 V$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 6.0 \text{ mA}; V_{CC} = 4.5 \text{ V}$	-	0.15	0.26	-	0.33	-	0.4	V
		$I_O = 7.8 \text{ mA}; V_{CC} = 6.0 \text{ V}$	-	0.16	0.26	-	0.33	-	0.4	V
I _I	input leakage current	$V_I = V_{CC}$ or GND; $V_{CC} = 6.0 \text{ V}$	-	-	±0.1	-	±1.0	-	±1.0	μА
l _{OZ}	OFF-state output current	per input pin; $V_I = V_{IH}$ or V_{IL} ; $V_O = V_{CC}$ or GND; other inputs at V_{CC} or GND; $V_{CC} = 6.0 \text{ V}$; $I_O = 0 \text{ A}$	-	-	±0.5	-	±5.0	-	±10	μА
I _{CC}	supply current	$V_I = V_{CC}$ or GND; $I_O = 0$ A; $V_{CC} = 6.0 \text{ V}$	-	-	8.0	-	80	-	160	μΑ
Cı	input capacitance		-	3.5	-	-	-	-	-	pF
74HCT2	44-Q100									
V_{IH}	HIGH-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	2.0	1.6	-	2.0	-	2.0	-	V
V_{IL}	LOW-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	-	1.2	0.8	-	0.8	-	0.8	V
V _{OH}	HIGH-level	$V_I = V_{IH}$ or V_{IL} ; $V_{CC} = 4.5 \text{ V}$								
	output voltage	$I_{O} = -20 \mu A$	4.4	4.5	-	4.4	-	4.4	-	V
		$I_O = -6 \text{ mA}$	3.98	4.32	-	3.84	-	3.7	-	V
V_{OL}	LOW-level	$V_I = V_{IH}$ or V_{IL} ; $V_{CC} = 4.5 \text{ V}$								
	output voltage	$I_O = 20 \mu A$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 6.0 \text{ mA}$	-	0.16	0.26	-	0.33	-	0.4	V
I _I	input leakage current	$V_I = V_{CC}$ or GND; $V_{CC} = 5.5 \text{ V}$	-	-	±0.1	-	±1.0	-	±1.0	μΑ
I _{OZ}	OFF-state output current	per input pin; $V_I = V_{IH}$ or V_{IL} ; $V_O = V_{CC}$ or GND; other inputs at V_{CC} or GND; $V_{CC} = 5.5$ V; $I_O = 0$ A	-	-	±0.5	-	±5.0	-	±10	μА
I _{CC}	supply current	$V_I = V_{CC}$ or GND; $V_{CC} = 5.5 \text{ V}; I_O = 0 \text{ A}$	-	-	8.0	-	80	-	160	μА
Δl _{CC}	additional supply current	per input pin; $V_I = V_{CC} - 2.1 \text{ V}$; other inputs at V_{CC} or GND; $V_{CC} = 4.5 \text{ V}$ to 5.5 V; $I_O = 0 \text{ A}$	-	70	252	-	315	-	343	μΑ
C _I	input capacitance		-	3.5	-	-	-	-	-	pF

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10. Dynamic characteristics

Table 7. Dynamic characteristics

GND = 0 V; for load circuit see Figure 8.

Symbol	Parameter	Conditions			25 °C		-40 °C to	Unit	
				Min	Тур	Max	Max (85 °C)	Max (125 °C)	
74HC24	4-Q100				1				
t _{pd} propagation dela		nAn to nYn;	<u>[1]</u>						
	see Figure 6								
	$V_{CC} = 2.0 \text{ V}$		-	30	110	145	165	ns	
		$V_{CC} = 4.5 \text{ V}$		-	11	22	28	33	ns
		$V_{CC} = 5.0 \text{ V}; C_L = 15 \text{ pF}$		-	9	-	-	-	ns
		$V_{CC} = 6.0 \text{ V}$		-	9	19	24	28	ns
t _{en} enable time	enable time	nOE to nYn; see Figure 7	[2]						
		$V_{CC} = 2.0 \text{ V}$		-	36	150	190	225	ns
		$V_{CC} = 4.5 \text{ V}$		-	13	30	38	45	ns
		$V_{CC} = 6.0 \text{ V}$		-	10	26	33	38	ns
dis	disable time	nOE to nYn or see Figure 7	[3]						
		$V_{CC} = 2.0 \text{ V}$		-	39	150	190	225	ns
		$V_{CC} = 4.5 \text{ V}$		-	14	30	38	45	ns
		$V_{CC} = 6.0 \text{ V}$		-	11	26	33	38	ns
t	transition time	see Figure 6	<u>[4]</u>						
		$V_{CC} = 2.0 \text{ V}$		-	14	60	75	90	ns
		$V_{CC} = 4.5 \text{ V}$		-	5	12	15	18	ns
		$V_{CC} = 6.0 \text{ V}$		-	4	10	13	15	ns
C _{PD}	power dissipation capacitance	per buffer; $V_I = GND$ to V_{CC}	<u>[5]</u>	-	35	-	-	-	pF

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Table 7. Dynamic characteristics ...continued GND = 0 V; for load circuit see Figure 8.

Symbol	Parameter	Conditions			25 °C		-40 °C to	+125 °C	Unit
				Min	Тур	Max	Max (85 °C)	Max (125 °C)	
74HCT2	44-Q100				•				
t _{pd} propagation dela		nAn to nYn;	<u>[1]</u>						
		see Figure 6							
		V _{CC} = 4.5 V		-	13	22	28	33	ns
		$V_{CC} = 5.0 \text{ V}; C_L = 15 \text{ pF}$		-	11	-	-	-	ns
t _{en}	enable time	$\overline{\text{OE}}$ to nYn; $V_{\text{CC}} = 4.5 \text{ V}$; see Figure 7	[2]	-	15	30	38	45	ns
t _{dis}	disable time	\overline{OE} to nYn; $V_{CC} = 4.5 \text{ V}$; see Figure 7	[3]	-	15	25	31	38	ns
t _t	transition time	V _{CC} = 4.5 V; see <u>Figure 6</u>	[4]	-	5	12	15	18	ns
C_{PD}	power dissipation capacitance	per buffer; $V_I = GND$ to $V_{CC} - 1.5 V$	<u>[5]</u>	-	35	-	-	-	pF

- [1] t_{pd} is the same as t_{PHL} and t_{PLH} .
- [2] t_{en} is the same as t_{PZH} and t_{PZL} .
- [3] t_{dis} is the same as t_{PHZ} and t_{PLZ} .
- [4] t_t is the same as t_{THL} and t_{TLH} .
- [5] C_{PD} is used to determine the dynamic power dissipation (P_D in μW):

 $P_D = C_{PD} \times V_{CC}{}^2 \times f_i \times N + \sum \left(C_L \times V_{CC}{}^2 \times f_o \right)$ where:

 f_i = input frequency in MHz;

fo = output frequency in MHz;

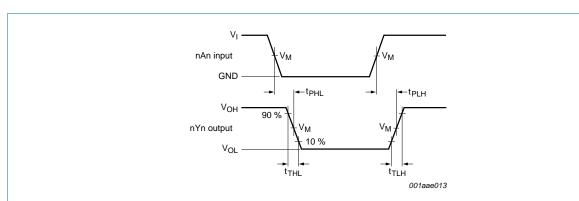
C_L = output load capacitance in pF;

 V_{CC} = supply voltage in V;

N = number of inputs switching;

 \sum (C_L × V_{CC}² × f_o) = sum of outputs.

11. Waveforms



Measurement points are given in Table 8.

 V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 6. Input (nAn) to output (nYn) propagation delays and output transition times

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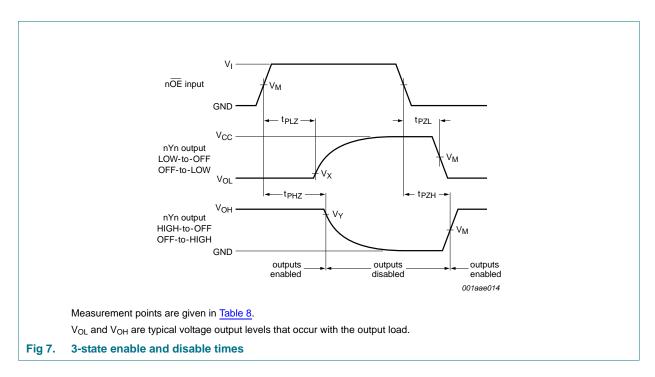
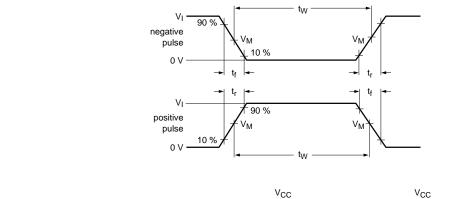
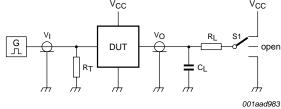


Table 8. Measurement points

Туре	Input	Output						
	V _M	V _M	V _X	V _Y				
74HC244-Q100	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	$0.1 \times V_{CC}$	$0.9 \times V_{CC}$				
74HCT244-Q100	1.3 V	1.3 V	$0.1 \times V_{CC}$	$0.9 \times V_{CC}$				

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Test data is given in Table 9.

Definitions test circuit:

 R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

 C_L = Load capacitance including jig and probe capacitance.

 R_1 = Load resistance.

S1 = Test selection switch.

Fig 8. Test circuit for measuring switching times

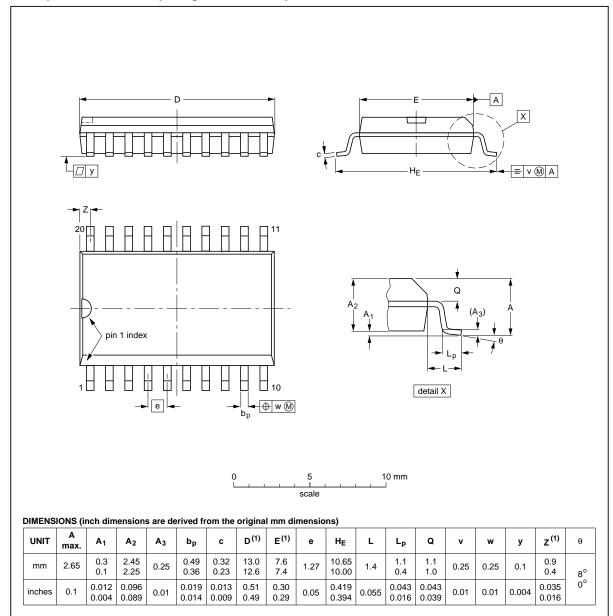
Table 9. Test data

Туре	Input		Load	Load		S1 position		
	V _I	t _r , t _f	CL	R _L	t _{PHL} , t _{PLH}	t _{PZH} , t _{PHZ}	t _{PZL} , t _{PLZ}	
74HC244-Q100	V_{CC}	6 ns	15 pF, 50 pF	1 k Ω	open	GND	V_{CC}	
74HCT244-Q100	3 V	6 ns	15 pF, 50 pF	1 kΩ	open	GND	V _{CC}	

12. Package outline

SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA	PROJECTION	1920E DATE	
SOT163-1	075E04	MS-013			99-12-27 03-02-19	

Fig 9. Package outline SOT163-1 (SO20)

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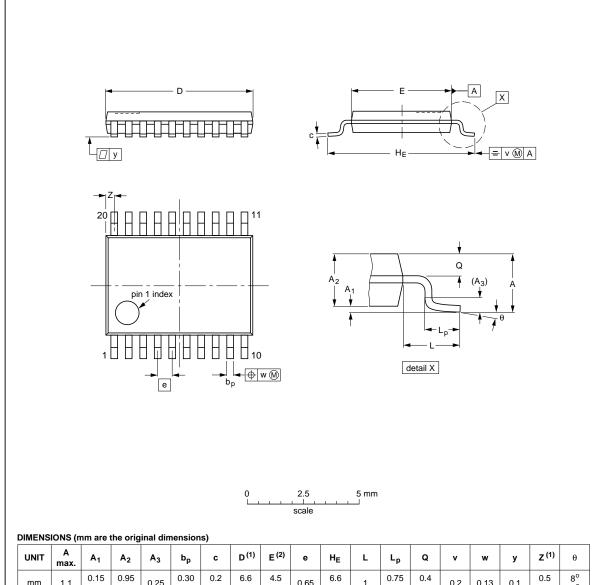
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TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1



UNIT	A max.	A ₁	A ₂	A ₃	bp	С	D ⁽¹⁾	E (2)	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE	
SOT360-1		MO-153				99-12-27 03-02-19	

Fig 10. Package outline SOT360-1 (TSSOP20)

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DHVQFN20: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 x 4.5 x 0.85 mm SOT764-1

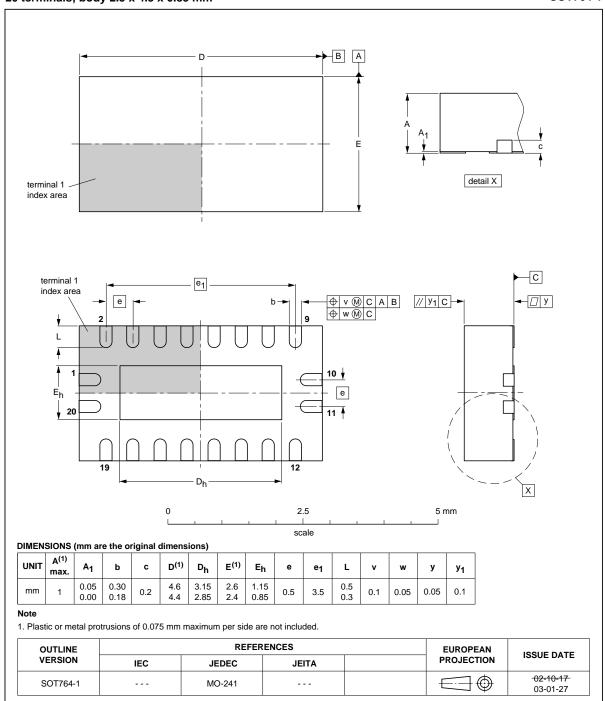


Fig 11. Package outline SOT764-1 (DHVQFN20)

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13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
НВМ	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic
MIL	Military

14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT244_Q100 v.1	20120807	Product data sheet	-	-

15. Legal information

15.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions"
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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